SLLS007D - JULY 1985 - REVISED APRIL 1998

 Meets or Exceeds the Requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11

Designed to Operate up to 20 Mbaud

- 3-State TTL Compatible
- Single 5-V Supply Operation
- High Output Impedance in Power-Off Condition
- Complementary Output-Enable Inputs
- Improved Replacement for the AM26LS31

#### D OR N PACKAGE (TOP VIEW) 16 V<sub>CC</sub> 1Y 🛮 2 15 1 4A 1Z**∏**3 14 **1** 4Y G **∏**4 13 **∏** 4Z 2Z 🛮 5 12 🛮 🗔 2Y [ 6 11 3Z 2A **∏** 7 10 3Y 9 **1** 3A GND [18

#### description

The four differential line drivers are designed for data transmission over twisted-pair or parallel-wire transmission lines. They meet the requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendations V.11 and are compatible with 3-state TTL circuits. Advanced low-power Schottky technology provides high speed without the usual power penalties. Standby supply current is typically only 26 mA, while typical propagation delay time is less than 10 ns.

High-impedance inputs maintain low input currents, less than 1  $\mu$ A for a high level and less than 100  $\mu$ A for a low level. Complementary output-enable inputs (G and  $\overline{G}$ ) allow these devices to be enabled at either a high input level or low input level. The SN75ALS192 is capable of data rates in excess of 20 Mbit/s and is designed to operate with the SN75ALS193 quadruple line receiver.

The SN75ALS192 is characterized for operation from 0°C to 70°C.

# FUNCTION TABLE (each driver)

INPUT	ENA	BLES	OUTPUTS				
Α	G	G	Υ	Z			
Н	Н	Х	Н	L			
L	Н	X	L	Н			
Н	Х	L	Н	L			
L	Х	L	L	Н			
Х	L	Н	Z	Z			

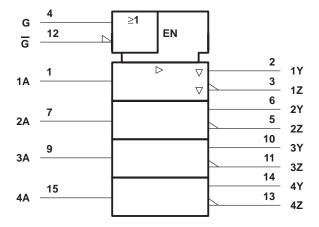
H = high level, L = low level, X = irrelevant, Z = high impedance (off)



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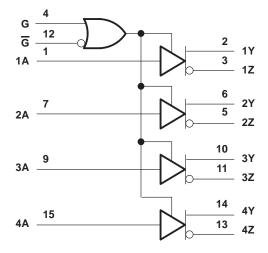


# logic symbol†



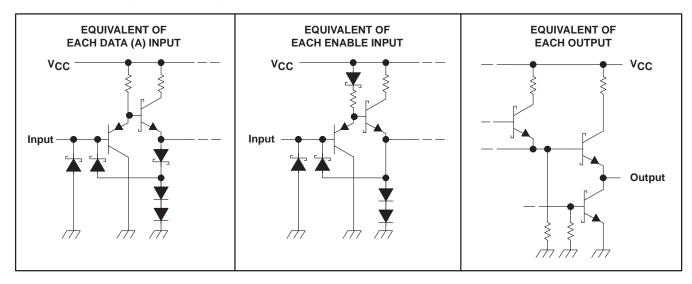
<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# logic diagram (positive logic)





## schematics of inputs and outputs



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)	7 V
Input voltage, V <sub>I</sub>	7 V
Off-state output voltage	6 V
Continuous total dissipation	See Dissipation Rating Table
Continuous total dissipation  Storage temperature range, T <sub>stg</sub> Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values except differential output voltage, VOD, are with respect to network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{\scriptsize A}} \le 25^{\circ}\mbox{\scriptsize C}$ POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D	950 mW	7.6 mW/°C	608 mW	N/A
N	1150 mW	9.2 mW/°C	736 mW	N/A

#### recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>	4.75	5	5.25	V
High level input voltage, V <sub>IH</sub>	2			V
Low-level input voltage, V <sub>IL</sub>			0.8	V
High-level output current, IOH			-20	mA
Low-level output current, IOL			20	mA
Operating free-air temperature, T <sub>A</sub>	0		70	°C



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## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS <sup>†</sup>		MIN	TYP‡	MAX	UNIT
VIK	Input clamp voltage	$V_{CC} = MIN,$	$I_{\parallel} = -18 \text{ mA}$			-1.5	V
Vон	High-level output voltage	$V_{CC} = MIN,$	$I_{OH} = -20 \text{ mA}$	2.5			V
VOL	Low-level output voltage	$V_{CC} = MIN,$	$I_{OL} = 20 \text{ mA}$			0.5	V
Vo	Output voltage	$V_{CC} = MAX$ ,	IO = 0	0		6	V
VOD1	Differential output voltage	$V_{CC} = MIN,$	IO = 0	1.5		6	V
V <sub>OD2</sub>	Differential output voltage	$R_L = 100 \Omega$ ,	See Figure 1	1/2 V <sub>OD1</sub> o	r 2§		V
Δ V <sub>OD</sub>	Change in magnitude of differential output voltage¶	R <sub>L</sub> = 100 Ω,	See Figure 1			±0.2	V
Voc	Common-mode output voltage#	$R_L = 100 \Omega$ ,	See Figure 1			±3	V
∆IVocI	Change in magnitude of common-mode output voltage¶	R <sub>L</sub> = 100 Ω,	See Figure 1			±0.2	V
lo.	Output current with power off	V <sub>C</sub> C = 0	V <sub>O</sub> = 6 V			100	
lo	Output current with power on	AGG = 0	$V_0 = -0.25 \text{ V}$			-100	μΑ
107	Off-state (high-impedance state) output current	V <sub>CC</sub> = MAX	V <sub>O</sub> = 0.5 V			-20	μΑ
loz	Oil-state (high-impedance state) output current	ACC = INIXX	V <sub>O</sub> = 2.5 V			20	μΑ
II	Input current at maximum input voltage	$V_{CC} = MAX$ ,	V <sub>I</sub> = 7 V			100	μΑ
lН	High-level input current	$V_{CC} = MAX$ ,	V <sub>I</sub> = 2.7 V			20	μΑ
I <sub>IL</sub>	Low-level input current	$V_{CC} = MAX$ ,	V <sub>I</sub> = 0.4 V			-200	μΑ
los	Short-circuit output current	$V_{CC} = MAX$	·	-30		-150	mA
Icc	Supply current (all drivers)	$V_{CC} = MAX$ ,	All outputs disabled		26	45	mA

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see Figure 2)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output	S1 and S2 open,	C <sub>L</sub> = 30 pF		6	13	ns
tPHL	Propagation delay time, high-to-low-level output	S1 and S2 open,	C <sub>L</sub> = 30 pF		9	14	ns
	Output-to-output skew	S1 and S2 open,	C <sub>L</sub> = 30 pF		3	6	ns
tPZH	Output enable time to high level	S1 open and S2 closed			11	15	ns
tpZL	Output enable time to low level	S1 closed and S2 open			16	20	ns
<sup>t</sup> PHZ	Output disable time from high level	S1 open and S2 closed,	C <sub>L</sub> = 10 pF		8	15	ns
tPLZ	Output disable time from low level	S1 and S2 closed,	C <sub>L</sub> = 10 pF		18	20	ns

 $<sup>^{\</sup>ddagger}$  All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

<sup>§</sup> The minimum  $V_{OD2}$  with a 100- $\Omega$  load is either 1/2  $V_{OD1}$  or 2 V, whichever is greater.

 $<sup>\</sup>P$  |VOD| and |VOC| are the changes in magnitude of VOD and VOC, respectively, that occur when the input is changed from a high level to a low level. # In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage,

Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

#### PARAMETER MEASUREMENT INFORMATION

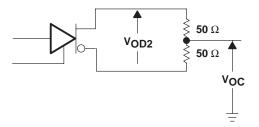
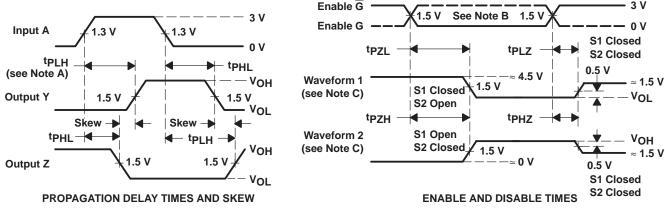
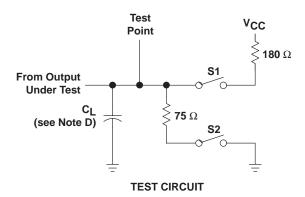


Figure 1. Differential and Common-Mode Output Voltages



**VOLTAGE WAVEFORMS** 



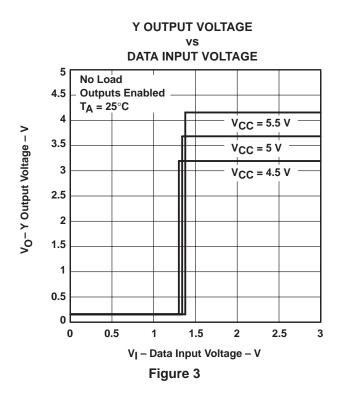
NOTES: A. When measuring propagation delay times and skew, switches S1 and S2 are open.

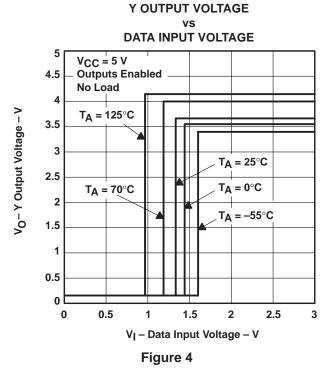
- B. Each enable is tested separately.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. C<sub>I</sub> includes probe and jig capacitance.
- E. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O \approx 50~\Omega,\,t_f \leq$  15 ns, and  $t_f \leq$  6 ns.

Figure 2. Test Circuit and Voltage Waveforms



## TYPICAL CHARACTERISTICS†





#### Y OUTPUT VOLTAGE **ENABLE G INPUT VOLTAGE** 4 $V_{CC} = 5.5 V$ 3.5 $V_{CC} = 5 V$ V<sub>O</sub>-Y Output Voltage - V 3 V<sub>CC</sub> = 4.5 V 2.5 2 1.5 1 $V_I = 2 V$ $R_L = 470 \Omega$ to GND 0.5 See Note A T<sub>A</sub> = 25°C 0 0 0.5 1 1.5 2 2.5 3 VI - Enable G Input Voltage - V

#### Y OUTPUT VOLTAGE **ENABLE G INPUT VOLTAGE** 5 V<sub>CC</sub> = 5 V $V_I = 2 V$ 4.5 $R_L = 470 \Omega$ to GND 4 See Note A V<sub>O</sub>- Y Output Voltage - V 3.5 T<sub>A</sub> = 125°C 3 $T_A = 25^{\circ}C$ 2.5 T<sub>A</sub> = 70°C $T_A = 0^{\circ}C$ 2 $T_A = -55^{\circ}C$ 1.5 1 0.5 0 0.5 1.5 0 2.5

NOTE A: The A input is connected to V<sub>CC</sub> during the testing of the Y outputs and to ground during the testing of the Z outputs.

NOTE A: The A input is connected to V<sub>CC</sub> during the testing of the Y outputs and to ground during the testing of the Z outputs.

V<sub>I</sub> - Enable G Input Voltage - V

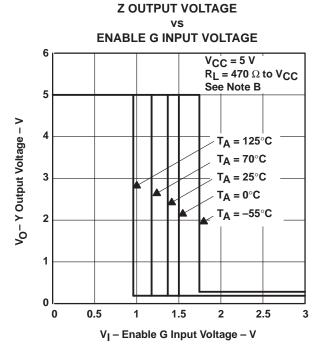
Figure 5

Figure 6

<sup>†</sup> Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

#### TYPICAL CHARACTERISTICS†

## **Z OUTPUT VOLTAGE** vs **ENABLE G INPUT VOLTAGE** 6 $R_L = 470 \Omega$ to $V_{CC}$ V<sub>CC</sub> = 5.5 V See Note A V<sub>CC</sub> = 5 V T<sub>A</sub> = 25°C 5 $V_{CC} = 4.5 V$ V<sub>O</sub>-Y Output Voltage - V 1 0 0 0.5 1.5 2 2.5 3 VI - Enable G Input Voltage - V



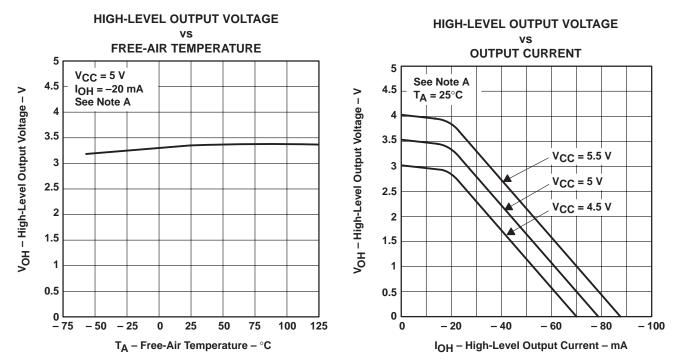
NOTE A: The A input is connected to  $V_{CC}$  during the testing of the Y outputs and to ground during the testing of the Z outputs.

NOTE B: The A input is connected to GND during the testing of the Y outputs and to  $V_{CC}$  during the testing of the Z outputs.

Figure 7 Figure 8

† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

#### TYPICAL CHARACTERISTICS<sup>†</sup>



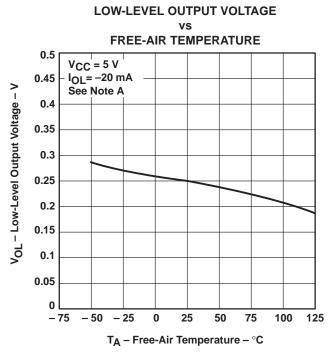
NOTE A: The A input is connected to V<sub>CC</sub> during the testing of the Y outputs and to ground during the testing of the Z outputs.

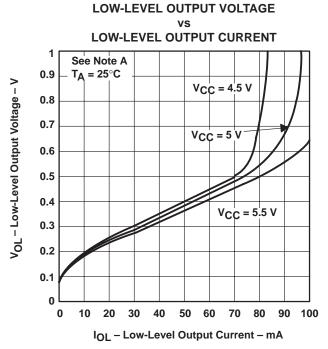
NOTE A: The A input is connected to V<sub>CC</sub> during the testing of the Y outputs and to ground during the testing of the Z outputs.

Figure 9 Figure 10

<sup>†</sup> Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

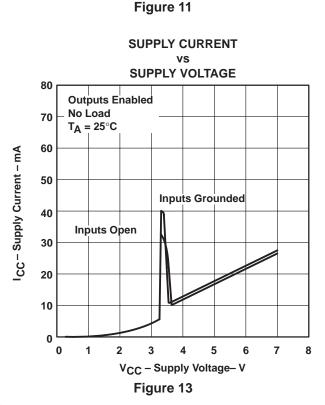
#### TYPICAL CHARACTERISTICS†



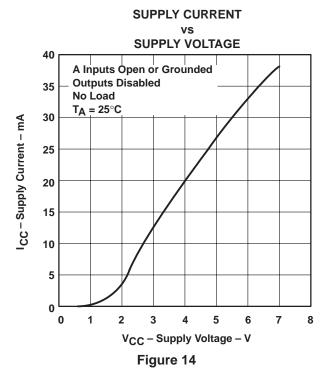


NOTE A: The A input is connected to GND during the testing of the Y outputs and to  $V_{\hbox{\footnotesize{CC}}}$  during the testing of the Z outputs.

NOTE A: The A input is connected to GND during the testing of the Y outputs and to V<sub>CC</sub> during the testing of the Z outputs.







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## TYPICAL CHARACTERISTICS

## SUPPLY CURRENT vs FREQUENCY

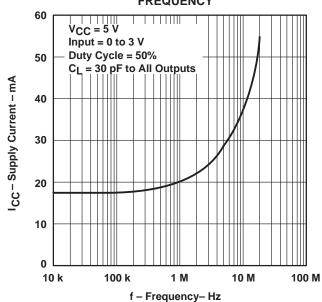


Figure 15

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